NUF2441FC

Integrated Passive Filter with ESD Protection

This device is designed for cell phone applications requiring Headset and Speaker Phone, EMI Filtering and ESD Protection. This device offers an integrated solution in a small package reducing PCB space and cost.

Features:

- Provides EMI Filtering and ESD Protection
- Single IC Offers Cost Savings by Replacing 2 Inductors, 4 Capacitors, and 4 TVs Diodes
- Compliance with IEC61000-4-2, (Level 4) 30 kV (Contact), 30 kV (air)
- Flip-Chip Package
- Moisture Sensitivity Level 1
- ESD Ratings: Machine Model = C Human Body Model = 3B
- Pb-Free Package is Available*

Benefits:

- Flip-Chip Package Minimizes PCB Space
- Integrated Circuit Increases System Reliability versus Discrete Component Implementation
- TVs Devices Provide ESD Protection That is Better than a Discrete Implementation because the Small IC minimizes Parasitic Inductances

Typical Applications:

- Cell Phones
- Communication Circuits

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
ESD Discharge IEC61000-4-2 Contact Discharge Air Discharge	V _{pp}	30 30	kV
Operating Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Lead Solder Temperature (10 second duration)	TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



ON Semiconductor®

http://onsemi.com

CIRCUIT DESCRIPTION _ B2 A3





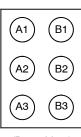
MARKING DIAGRAM

Flip-Chip CASE 499J

> = Specific Device Code = Assembly Location

= Year = Work Week

PIN CONFIGURATION



(Bump View)

ORDERING INFORMATION

Package	Device	Shipping [†]
NUF2441FCT1	Flip-Chip	3000/Tape & Reel
NUF2441FCT1G	Flip-Chip (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

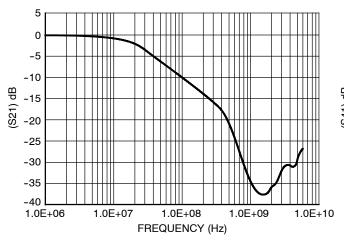
^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NUF2441FC

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

	Device	V _{RWM}		ર @ nA Its)	Max I _R @ V _{RWM} = 12 V I/O Pin	Typical Capacitance C ₁ + C ₂ (pF)	Typical Pass-Band Inductance	Equivalent Series Resistance R _S (Ω) (Note 2)	
Device	Marking	(Volts)	Min	Max	(μΑ)	(Notes 1, 3, 4)	L (nH)	Тур	Max
NUF2441FCT1G	2441	12	13.7	17.7	0.1	250	2.9	0.28	0.35

- 1. Measured at 25°C, V_R = 0, f = 1 MHz, Source A1, GND A2, Open A3. 2. Measured at room temperature.
- Tolerance = $\pm 20\%$.
- 4. Measured under zero light conditions.



0 -10 -20 (S41) dB -30 -40 -50 -60 1.0E+06 1.0E+07 1.0E+08 1.0E+09 1.0E+10 FREQUENCY (Hz)

Figure 1. Insertion Loss Characteristic

Figure 2. Analog Crosstalk

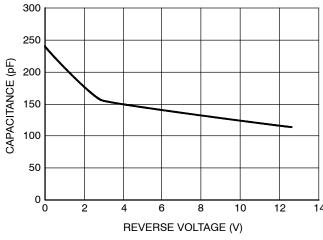


Figure 3. Typical Line Capacitance vs. Reverse Bias Voltage

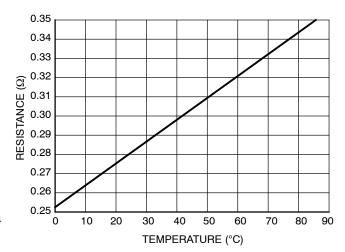


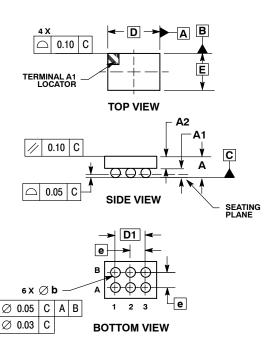
Figure 4. Typical Resistance vs. Temperature





6 PIN FLIP-CHIP 1.72x1.22mm, 0.5 PITCH CASE 499J-01 **ISSUE O**

DATE 05 FEB 2004



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL
- CROWNS OF SOLDER BALLS.

	MILLIMETERS				
DIM	MIN	MAX			
Α		0.700			
A1	0.210	0.270			
A2	0.380	0.430			
D	1.720 BSC				
Е	1.220 BSC				
b	0.290	0.340			
е	0.500 BSC				
D1	1.000 BSC				

GENERIC MARKING DIAGRAM*



= Specific Device Code XX = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking.

DOCUMENT NUMBER:	98AON13950D	Electronic versions are uncontrolled except when accessed directly from the Document Reposi Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	6 PIN FLIP-CHIP, 1.72x1.22mm, 0.5 PITCH		PAGE 1 OF 1

ON Semiconductor and at a trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer pu

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for ESD Suppressors / TVS Diodes category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below:

60KS200C D12V0H1U2WS-7 D18V0L1B2LP-7B 82356050220 D5V0M5U6V-7 NTE4902 P4KE27CA P6KE11CA P6KE39CA-TP
P6KE8.2A SA110CA SA60CA SA64CA SMBJ12CATR SMBJ8.0A SMLJ30CA-TP ESD101-B1-02ELS E6327 ESD112-B1-02EL E6327
ESD119B1W01005E6327XTSA1 ESD5V0J4-TP ESD5V0L1B02VH6327XTSA1 ESD7451N2T5G 19180-510 CPDT-5V0USP-HF
3.0SMCJ33CA-F 3.0SMCJ36A-F HSPC16701B02TP D3V3Q1B2DLP3-7 D55V0M1B2WS-7 DESD5V0U1BL-7B DRTR5V0U4SL-7
SCM1293A-04SO ESD200-B1-CSP0201 E6327 ESD203-B1-02EL E6327 SM12-7 SMF8.0A-TP SMLJ45CA-TP CEN955 W/DATA
82350120560 82356240030 VESD12A1A-HD1-GS08 CPDUR5V0R-HF CPDUR24V-HF CPDQC5V0U-HF CPDQC5V0USP-HF
CPDQC5V0-HF D1213A-01LP4-7B D1213A-02WL-7 ESDLIN1524BJ-HQ 5KP100A